

ABSTRACT

The present invention provides a method of manufacturing a circuit board module for connecting a circuit conductor (2) of a first circuit board (1) to a circuit conductor (4) of a second circuit board (5) using at least one selected from the group consisting of an anisotropic conductive film (6), an anisotropic conductive paste and an adhesive resin, wherein a difference in a pattern width between the circuit conductor of the first circuit board and that of the second circuit board is in a range of 5 μm to 50 μm . In such a method of manufacturing a circuit board module, connection of a connecting conductor with a narrow pitch can be realized, and poor connection can be reduced, thus providing a method of manufacturing a circuit board module having higher reliability.



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